

**AMENDMENT TO THE ABSTRACT**

Please amend the Abstract of the Disclosure to read as follows.

--A scribe method for a brittle material substrate is a method in which a plurality of scribe lines are formed in directions intersecting with one another in a surface of the brittle material substrate, wherein at least one scribe line in a first direction is formed by a ~~scribe means~~ cutter wheel generating a high-penetration vertical crack in the brittle material substrate by applying impacts of a short period to the point on the surface of the brittle material substrate. After this, at least one scribe line of a second direction in a direction intersecting with the at least one scribe line of the first direction is formed with the ~~scribe means~~ cutter wheel by scribing without producing intersections with the scribe lines of the first direction.--